REPLACEMENT SHEET
30 SEP 2002

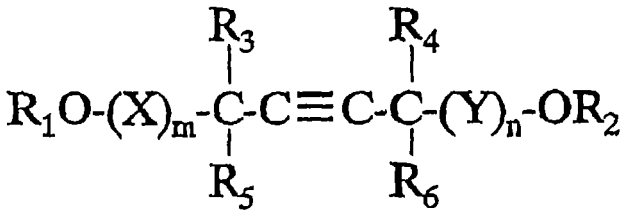
POLISHING COMPOSITION AND POLISHING METHOD EMPLOYING IT

ABSTRACT

A polishing composition comprising:

(a) at least one abrasive selected from the group consisting of silicon dioxide and aluminum oxide,

(b) at least one organic compound selected from the group consisting of a polyethylene oxide, a polypropylene oxide, a polyoxyethylene alkyl ether, a polyoxypropylene alkyl ether, a polyoxyethylenepolyoxypropylene alkyl ether and a polyoxyalkylene addition polymer having a C≡C triple bond, represented by the formula (1):



wherein each of R_1 to R_6 is a C_{1-10} alkyl group, each of X and Y is an ethylene group or a propylene group, and each of m and n is a positive number of from 1 to 20,

(c) at least one polishing accelerating compound selected from the group consisting of citric acid, oxalic acid, tartaric acid, glycine, α-alanine and histidine,

(d) at least one anticorrosive selected from the group consisting of benzotriazole, benzimidazole, triazole, imidazole and tolyltriazole,

(e) hydrogen peroxide, and

(f) water.

Figure 1

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